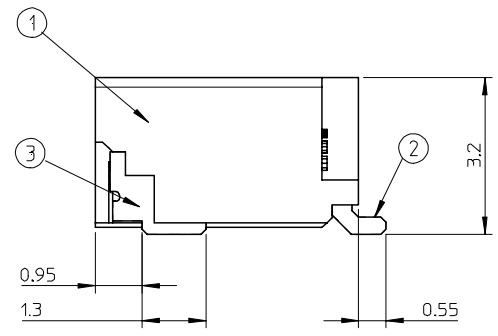
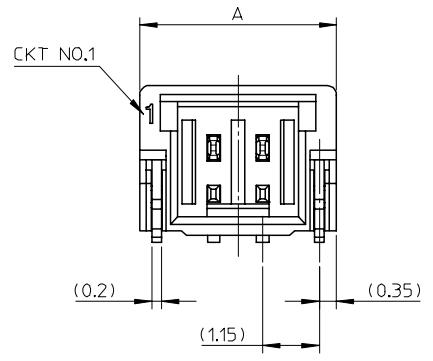


参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



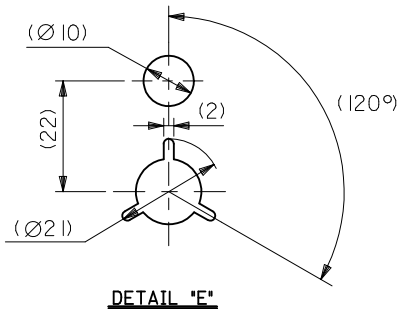
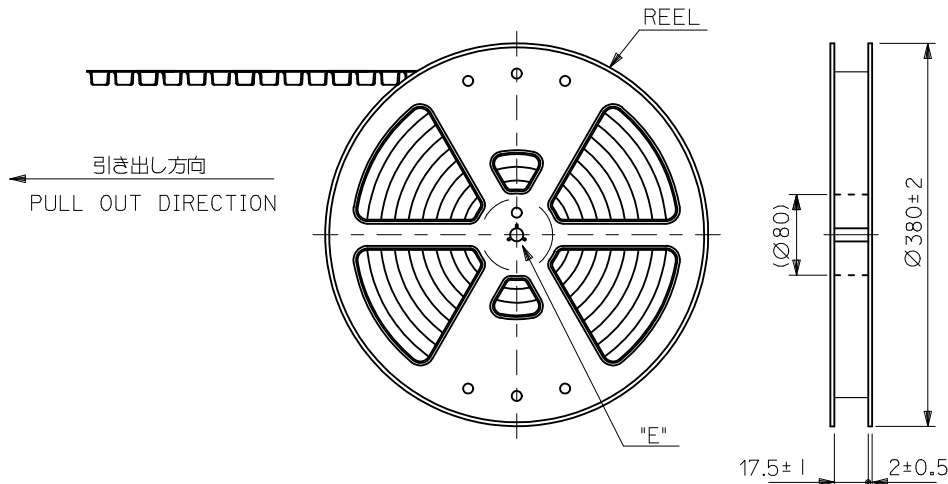
番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0、色：自然色 HEAT RESISTANCE NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	リン青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

4.0	7.0	501568-0509	5	501568-**09
3.0	6.0	501568-0409	4	
2.0	5.0	501568-0309	3	
1.0	4.0	501568-0209	2	
B	A	MATERIAL NO.	CKT	MODEL NO.

NOTES

- かん合相手 : 501330-****
MATE WITH : 501330-****
- ソルダーピン及びネイルの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
- 6~15極は、SD-501568-002を参照下さい。
REFER TO SD-501568-002 ABOUT 6-15CKT.

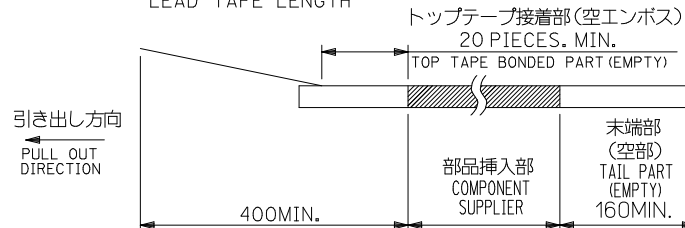
REVISED EC NO: J2008-0220 DRW: NABEI 2007/07/25 CHK: KYOYODA 2007/07/27 APP: NUKITA 2007/07/27	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 2-5CKT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/19			
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/19	MOLEX INCORPORATED		
ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO. SD-501568-001	SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



NOTES

- 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
- 梱包数量：1700個/リール
NUMBER OF CONNECTORS：1700PIECES/REEL

- リードテープ長さ
LEAD TAPE LENGTH



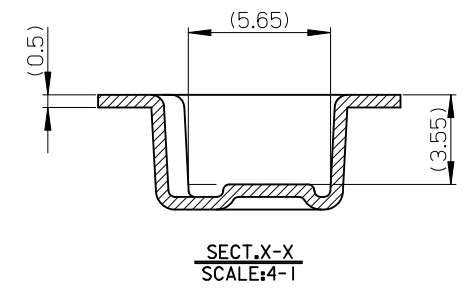
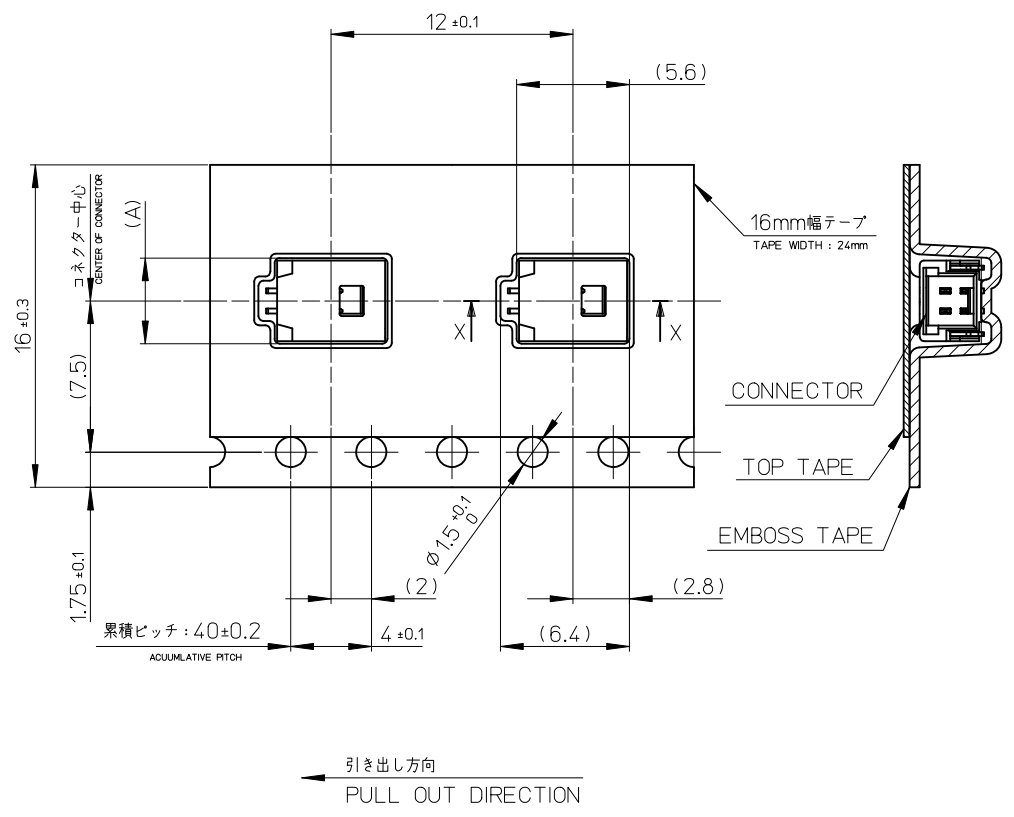
- 材料

MATERIAL
 キャリアテープ：ポリプロピレン
 CARRIER TAPE：POLYPROPYLENE
 トップテープ：PET、PE、REF
 TOP TAPE
 リール：ポリスチレン<リサイクル材を含む>
 REEL：POLYSTYRENE <RECYCLE MATERIAL CONTAINED>

- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(501568-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 501568-0607~1507)

REVISED EC NO: J2010-0951 DRWN: NITO 2009/12/16 CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/11/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/11/26			
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/11/26	MOLEX INCORPORATED		
ANGULAR ±1 °		MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501568-005	SHEET NO. 1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



7.3	501568-0509	501568-0507	5
6.3	501568-0409	501568-0407	4
5.3	501568-0309	501568-0307	3
4.3	501568-0209	501568-0207	2
(A)	CONNECTOR	MATERIAL NO.	CKTS.

REVISED EC NO: J2010-0951 DRWN: NITO 2009/12/16 CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY AMIZUMURA	DATE 2005/11/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/11/26	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/11/26	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-501568-005	SHEET NO. 2 OF 2
	ANGULAR ±3 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						